

3mm Two Position CBI Housing

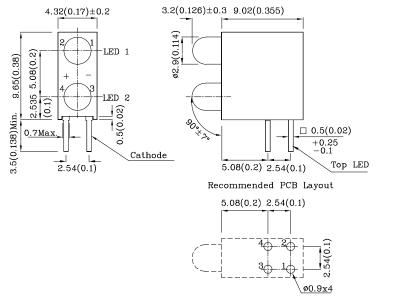
Features

- \bullet Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- Custom color combinations available
- RoHS Compliant





Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

| Absolute Maximum Ratings (T _A =25°C) | | Yellow (GaAsP/GaP) | Unit | | |
|--|---------------------|-----------------------|------|--|--|
| Reverse Voltage | V_{R} | 5 | V | | |
| Forward Current | I_{F} | 30 | mA | | |
| Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width | ifs | 140 | mA | | |
| Power Dissipation | P_{D} | 75 | mW | | |
| Operating Temperature | $T_{\rm A}$ | -40 ~ +85 | °C | | |
| Storage Temperature | Tstg | -40 ~ +85 | | | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3 Seconds | | | | |
| Lead Solder Temperature [5mm Below Package Base] | 260°C For 5 Seconds | | | | |

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

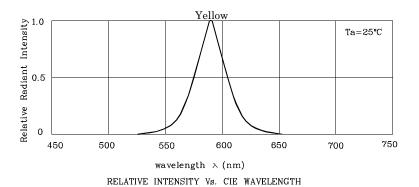
| Operating Characteristics (T _A =25°C) | | Yellow (GaAsP/GaP) | Unit |
|--|------------------|-----------------------|------|
| Forward Voltage (Typ.) (I _F =10mA) | V_{F} | 1.95 | V |
| Forward Voltage (Max.) (I _F =10mA) | V_{F} | 2.5 | V |
| Reverse Current (Max.) $(V_R=5V)$ | I_R | 10 | uA |
| Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA) | λР | 590* | nm |
| Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA) | λD | 588* | nm |
| Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA) | Δλ | 35 | nm |
| Capacitance (Typ.) (V _F =0V, f=1MHz) | С | 20 | pF |

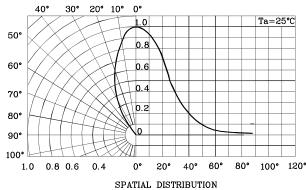
| Part Number | Emitting Color | Emitting Material | Lens-color | $\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=}10\text{mA)} \\ \text{mcd} \end{array}$ | | Wavelength CIE127-2007* nm λP | Viewing Angle 2θ 1/2 |
|----------------|-------------------|----------------------|-----------------|---|------|--|----------------------------|
| | | | | min. | typ. | | |
| XVG2LUY11D | Yellow | GaAsP/GaP | Yellow Diffused | 8* | 14* | 590* | 50° |

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

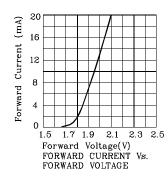


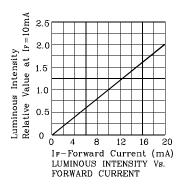


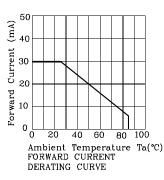


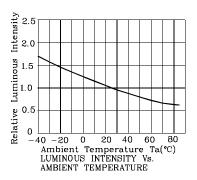


❖ Yellow

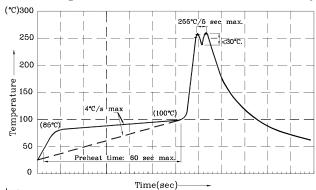








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C$ \sim $255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

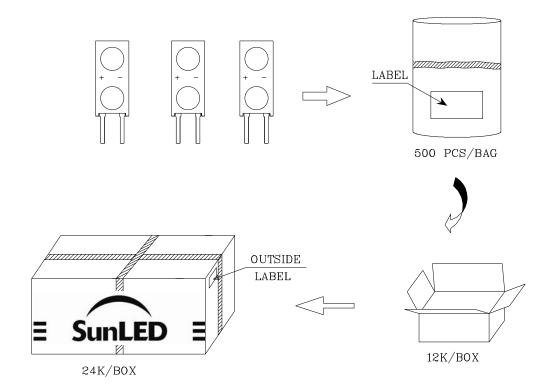
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

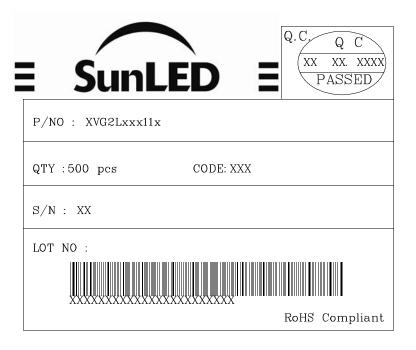
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

XDSB8827 V2-Z Layout: Maggie L.